

English Abstract of Cited Device 4

[Korean Laid-open Patent Publication No. 2000-18619 (Apr. 6, 2000)]

TITLE: POLISHING HEAD OF CMP EQUIPMENT FOR PRODUCING A SEMICONDUCTOR DEVICE

Abstract:

The subject invention relates to a polishing head of CMP equipment which enables to adsorb a wafer in the polishing head of CMP equipment for producing a semiconductor device, or to easily exhaust slurries remaining in the retainer to the outside.

As illustrated in Fig. 4, the polishing head of CMP equipment for producing a semiconductor device according to the subject invention additionally forms an extension (21) toward the inside terminal of a retainer (10) of a slurry exhaustion hole formed in the retainer (10) to the polishing head of the conventional CMP equipment comprising a retainer (10) wherein a slurry exhaustion hole (11) is formed horizontally.

Thus, the subject invention can exhaust slurries (13) rapidly and sufficiently to the outside of the retainer (10), so that enough vacuous state can be made at the time of adsorbing a wafer (12), and thereby making the adsorption of a wafer (12) perfect so that damage of the wafer (12) can be prevented.